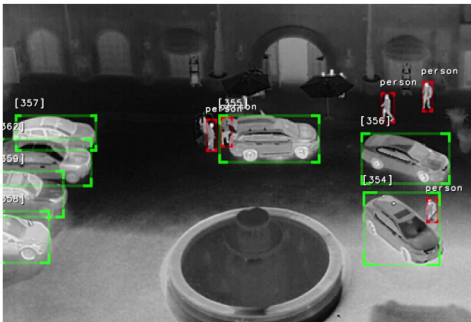


Prism™ Development Kit for Qualcomm® RB5



The Prism Development Kit for Qualcomm RB5 enables system engineers to evaluate Prism ISP and Prism AI with the output of Teledyne FLIR's Hadron™ thermal imaging camera modules. Prism ISP software includes image fusion, super resolution, turbulence mitigation, electronic imaging stabilization, 16-to-8-bit tone mapping, and local contrast enhancement (LCE). Prism AI features a mature perception software that includes object classification, object detection, object tracking, and fine-grained classification trained on the world's largest thermal and visible image data lake with over 5 million annotation assets.

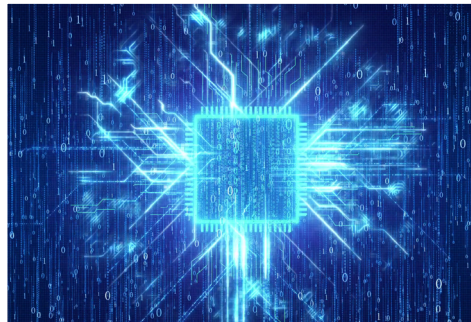
The development kit includes Teledyne FLIR's Hadron dual visible and thermal camera module, all necessary cables, and the Qualcomm Robotics RB5 QRB5165 system on chip (SoC), the most popular and efficient mobile processor for digital imaging, bringing unprecedented capabilities to Teledyne FLIR thermal camera module integrators.



EVALUATE ADVANCED COMPUTATIONAL IMAGING AND EDGE AI

Get started with thermal infrared object detectors and advanced image signal processing.

- Air-to-ground, automotive autonomy, counter UAS, and security/Ground ISR models
- Preinstalled libraries simplify perception and computational imaging evaluation
- AI DSP co-processor with 3 TOPS and 8 TOPS on the Hexagon™ Tensor Accelerator (HTA) for running models at 8INT
- Web interface



DEVELOP ON THE QUALCOMM ROBOTICS RB5 PLATFORM

Utilize the flexible and most popular mobile SoC.

- 15 TOPS compute power
- 8 CPU cores
- USB and MIPI camera interfaces
- 16 GB LPDDR5 up to 2750 MHz and LPDDR4X up to 2133 MHz
- 1 x 1GbE Ethernet



DESIGNED FOR INTEGRATORS

Simplify development and reduce risk with Prism software and support.

- SDK for Linux 20.04 OS
- Development support by qualified engineers
- Sample applications included
- Ongoing AI model development using the industry's largest thermal data lake

FEATURES

Processor	<ul style="list-style-type: none"> AI DSP co-processor with 3 TOPS and 8 TOPS on the Hexagon™ Tensor Accelerator (HTA) for running models at 8INT 15 TOPS total compute power 8 CPU cores
Memory	16 GB LPDDR5 up to 2750 MHz and LPDDR4X up to 2133 MHz
Camera Interfaces	USB and MIPI
Ethernet	1 x 1GbE Ethernet
Operating System	SDK for Linux 20.04
AI Models	Air to Ground, Counter UAS, Ground ISR, Security, Automotive Autonomy
ISP Libraries	Turbulence Mitigation, Super Resolution, Electronic Stabilization, 16-8 bit Tone Mapping, Denoise
Part Number	421-0100-00

Specifications are subject to change without notice.
For the most up-to-date specs, go to www.flir.com/RB5devkit

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